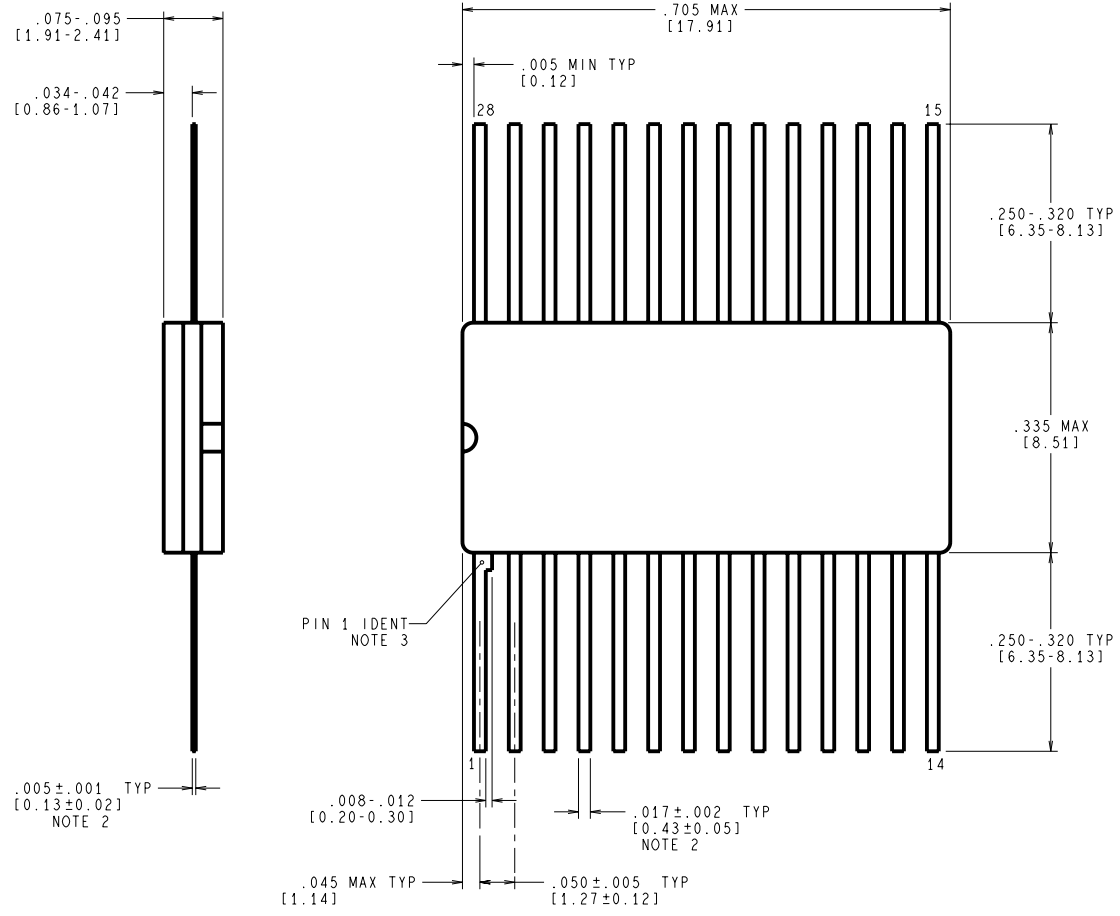


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
D	REVISE AND REDRAW PER CURRENT STANDARD; UPDATE TITLE & MIL/AERO STAMP.	11047	07/14/95	MS/



PIN 1 IDENT
NOTE 3

CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO A MINIMUM THICKNESS OF 200 MICRONS/ 5.08 MICROMETERS. SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE.
- LEAD THICKNESS MAY BE INCREASED BY .003 INCHES/ 0.08 MILLIMETERS MAXIMUM AFTER LEAD FINISH APPLIED.
- LEAD 1 IDENTIFICATION SHALL BE:
 - A NOTCH OR OTHER MARK WITHIN THIS AREA
 - A TAB ON LEAD 1, EITHER SIDE
- REFERENCE JEDEC REGISTRATION MO-019, VARIATION AD, DATED 9/20/77.

MIL-PRF-38535
CONFIGURATION CONTROL

APPROVALS	DATE	National Semiconductor			
DRAWN MARTA SUCHY	07/14/95	2900 Semiconductor dr., Santa Clara, CA 95052-8090			
DTG. CHK.		CERPAC, 28 LEAD			
ENGR. CHK.					
		SCALE N/A	SIZE C	DRAWING NUMBER MKT-W28A	REV D
		DO NOT SCALE DRAWING		SHEET 1 of 1	